# LMMS PACKAGING STANDARD



## Packaging of Active & Passive Bare Die and Chips

### 1.0 SCOPE

This standard establishes the minimum acceptable methods of packaging bare die and chips. The components may be active or passive and may or may not be ESD sensitive. This standard does not normally allow for individual packaging of these components.

### 2.0

2.4 Intermediate Packaging

2.4.1 Intermediate Packaging shall be consistent with good standard commercial packaging practices.

2.5 Packing (Shipping Container)

2.5.1 Packing shall protect each item and package during ordinary handling and shipping and shall meet the minimum requirements of the common carriers for safe transportation in an economic manner.

2.6 Marking

2.6.1 Marking of the Unit Package shall include:

Quantity per Unit Package

Part Number per contracting document

Purchase Order Number